

EXP-355

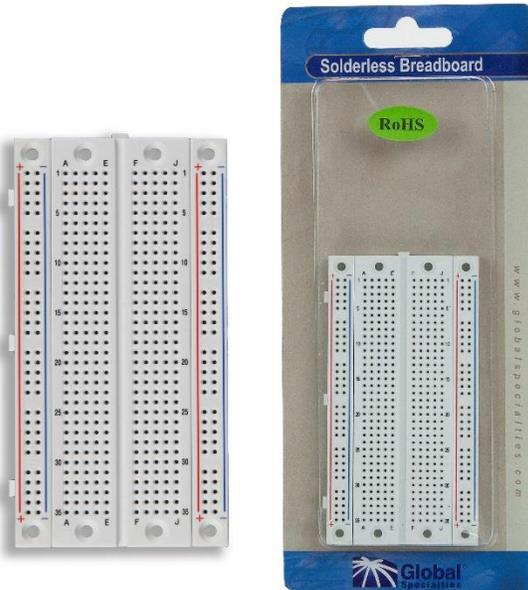
Solderless Breadboard, 470 Tie-Points

Solderless Breadboards

Phosphor bronze contacts

High impact plastic

Heavy-duty Mylar backing



Overview:

The Global Specialties EXP-355 has 470 tie-points and offers unlimited circuit design expansion through its unique molded-in interlocking edge rails. It offers 0.3" DIP spacing, and its unique molded-in mounting holes allow for either front or rear mounting. Molded interlocking edge rails on all four sides permit parallel or perpendicular socket arrays, allowing more boards to be added at any point for maximum circuit design flexibility. The integrated bus strips allow for fast connections to power and signal lines. The EXP-355 is made from high impact plastic with phosphor bronze contacts. It has a heavy-duty Mylar backing to prevent short circuits.

Specifications

Type	Solderless Breadboard
Tie-Points	470
Terminal Clips	94
Breadboard Material	ABS
Spring Clip Material	Nickel plated phosphor bronze
Length	4.12 in
Width	2.31 in
Depth	8 mm (0.33 in)
Assembly	NA
Current Capacity	1.5 A, 36 V
16-Pin IC Capacity	5



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